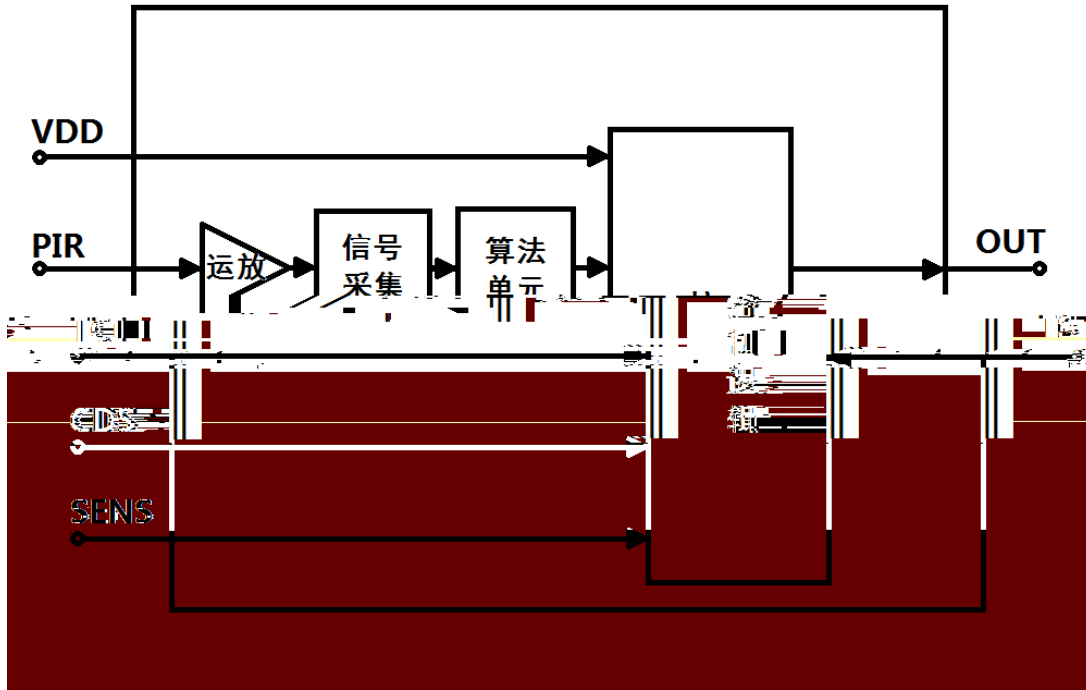
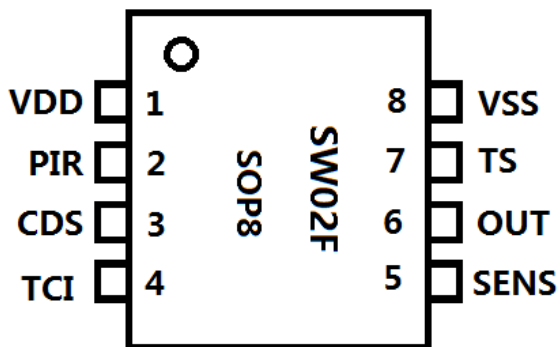


IC

IC



SW02F SOP8



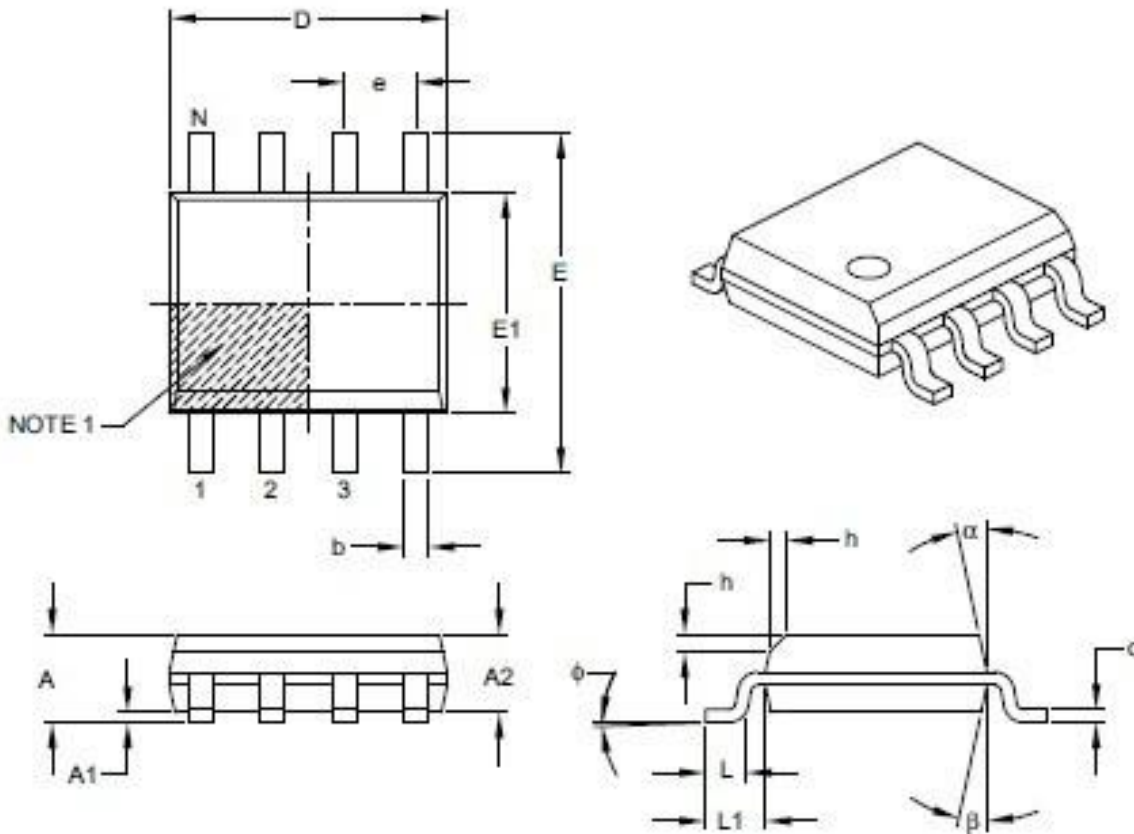
IC

1	VDD	
2	PIR	PIR
3	CDS	CDS VDD*1/3 IC VDD*1/3 IC R2 R2
4	TCI	OUT SW02F
5	SENS	0~0.1V 3.3V 1.7V~2.5V
6	OUT	15
7	TS	TS 13 TCI TS VSS TCI
8	VSS	

	V _{DD}	2.4	3.3	3.6	V	—
	I _{DD}		198		uA	VDD = 3.3V TS
V _{OUT}	I _{OH}			10	mA	VDD = 3.3V V _{OL} = 0.3V
	Temp.	-40	25	85		—
	Temp.	-65	25	150		—

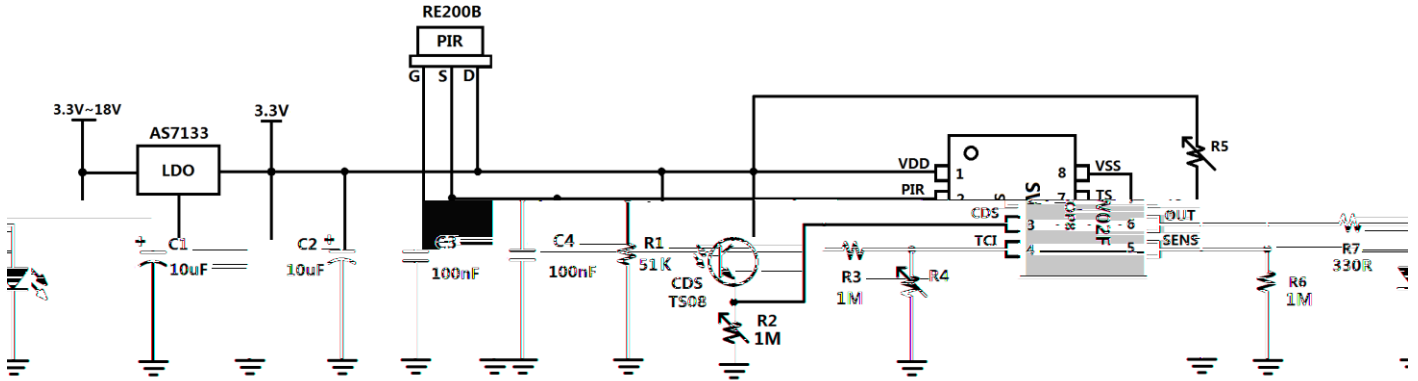
IC

SOP8



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		1.27 BSC		
Overall Height	A		-	-	1.75
Molded Package Thickness	A2		1.25	-	-
Standoff \S	A1		0.10	-	0.25
Overall Width	E		6.00 BSC		
Molded Package Width	E1		3.90 BSC		
Overall Length	D		4.90 BSC		
Chamfer (optional)	h		0.25	-	0.50
Foot Length	L		0.40	-	1.27
Footprint	L1		1.04 R		
Foot Angle	ϕ		0°	-	8°
Lead Thickness	c		0.17	-	0.25
Lead Width	b		0.31	-	0.51
Mold Draft Angle Top	α		5°	-	15°
Mold Draft Angle Bottom	β		5°	-	15°

IC



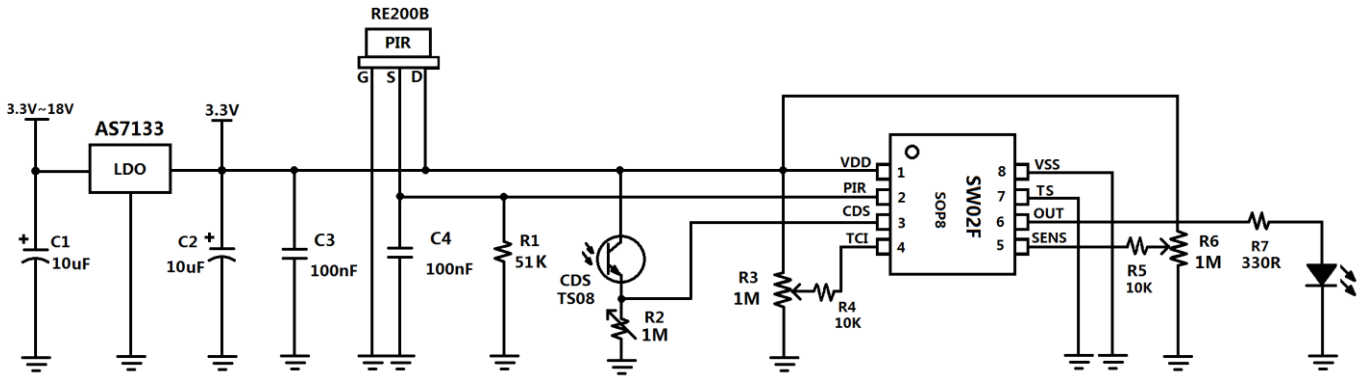
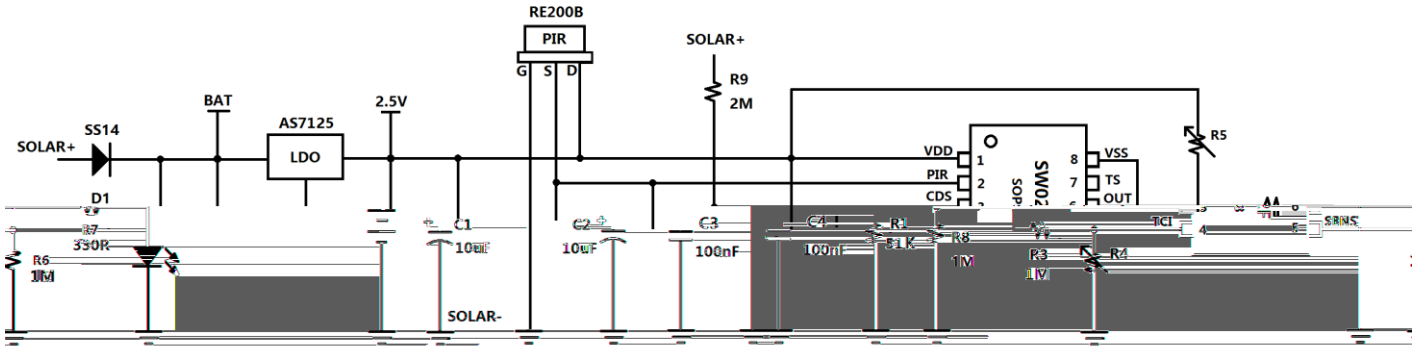
TS

R4

13

R4	Ω	
		1
2M		1
1M		5
910K		10
820K		15
750K		20
680K		30
560K		45
470K		60
390K		90
300K		120
200K		180
100K		300
0		480

IC



TS VSS R4

TCI	TCI	VDD	600
TCI	TCI	VSS	2



PIR
SW02F

IC

1 PIR SENSER SW02F

2 PCB

3

4